



TOSHIBA AMERICA ELECTRONIC COMPONENTS INC.

To: Distribution Channel

July 2014

Please be informed that Toshiba has announced discontinuation on the following Small Signal devices in July 2014. Toshiba will change the production site from Amkor Technology (Malaysia) to the Toshiba Semiconductor (Thailand) Co. Our sales records indicate you have purchased the following product(s) from Toshiba in the past.

- ※There is no change for electrical characteristics specification and reliability.
- ※For attached items, the wire-bonding material, Lead Frame material and generic item name is slightly modified.
- ※The recommended product for new design is Thailand assembly version.

### **Reason**

Since the flood in November 2011, Toshiba recovery plans resulted in restarting our semiconductor manufacturing operations in Thailand; Toshiba Semiconductor Thailand Co., Ltd. (TST). Our new Thailand assembled products are currently in full production and our capacity is increasing. TST is currently our main factory for Small Signal Devices and will continue to provide high quality, improved cost, and continuity of supply improvements for our customer base.

### **Malaysia Products Impacted With Replacement Suggestion From Thailand**

Please see attachment.

### **Last Time Buy (LTB) Option**

Toshiba will support last time buy (LTB) orders received on or before September-30-2014 with last ship (LS) date of December-31-2014. Last time buy orders for all affected products must be in place in total by the LTB Date. Deliveries will be scheduled and advised accordingly after receipt of LTB orders. However, unforeseen circumstances might prevent Toshiba to support partially or fully on LTB orders. If such event occurs, we will notify you of our best support plan as soon as possible. Thank you for your understanding. Should you have any questions, please contact your sales representative.

Best Regards,

Logic Device, Discrete Business Unit  
Toshiba America Electronics Components, Inc.

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Substitution Level\*\*

- 0 = No replacement
- 1 = Package and characteristics are mostly same or better, not necessary to change other circuit to replace.
- 2 = Package and characteristics are mostly same or better, but some modification of the other circuit is necessary.
- 3 = Characteristics are same or better, but package/pin arrangement are different, so the other circuit modification is necessary.
- 4 = Other reason